

SSD1306

Advance Information

**128 x 64 Dot Matrix
OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.



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1 GENERAL DESCRIPTION

SSD1306 is a single-chip CMOS OLED/PLED driver with controller for organic / polymer light emitting diode dot-matrix graphic display system. It consists of 128 segments and 64 commons. This IC is designed for Common Cathode type OLED panel.

The SSD1306 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. It has 256-step brightness control. Data/Commands are sent from general MCU through the hardware selectable 6800/8000 series compatible Parallel Interface, I²C interface or Serial Peripheral Interface. It is suitable for many compact portable applications, such as mobile phone sub-display, MP3 player and calculator, etc.

2 FEATURES

- Resolution: 128 x 64 dot matrix panel
- Power supply
 - V_{DD} = 1.65V to 3.3V for IC logic
 - V_{CC} = 7V to 15V for Panel driving
- For matrix display
 - OLED driving output voltage, 15V maximum
 - Segment maximum source current: 100uA
 - Common maximum sink current: 15mA
 - 256 step contrast brightness current control
- Embedded 128 x 64 bit SRAM display buffer
- Pin selectable MCU Interfaces:
 - 8-bit 6800/8080-series parallel interface
 - 3 / 4 wire Serial Peripheral Interface
 - I²C Interface
- Screen saving continuous scrolling function in both horizontal and vertical direction
- RAM write synchronization signal
- Programmable Frame Rate and Multiplexing Ratio
- Row Re-mapping and Column Re-mapping
- On-Chip Oscillator
- Chip layout for COG & COF
- Wide range of operating temperature: -40°C to 85°C

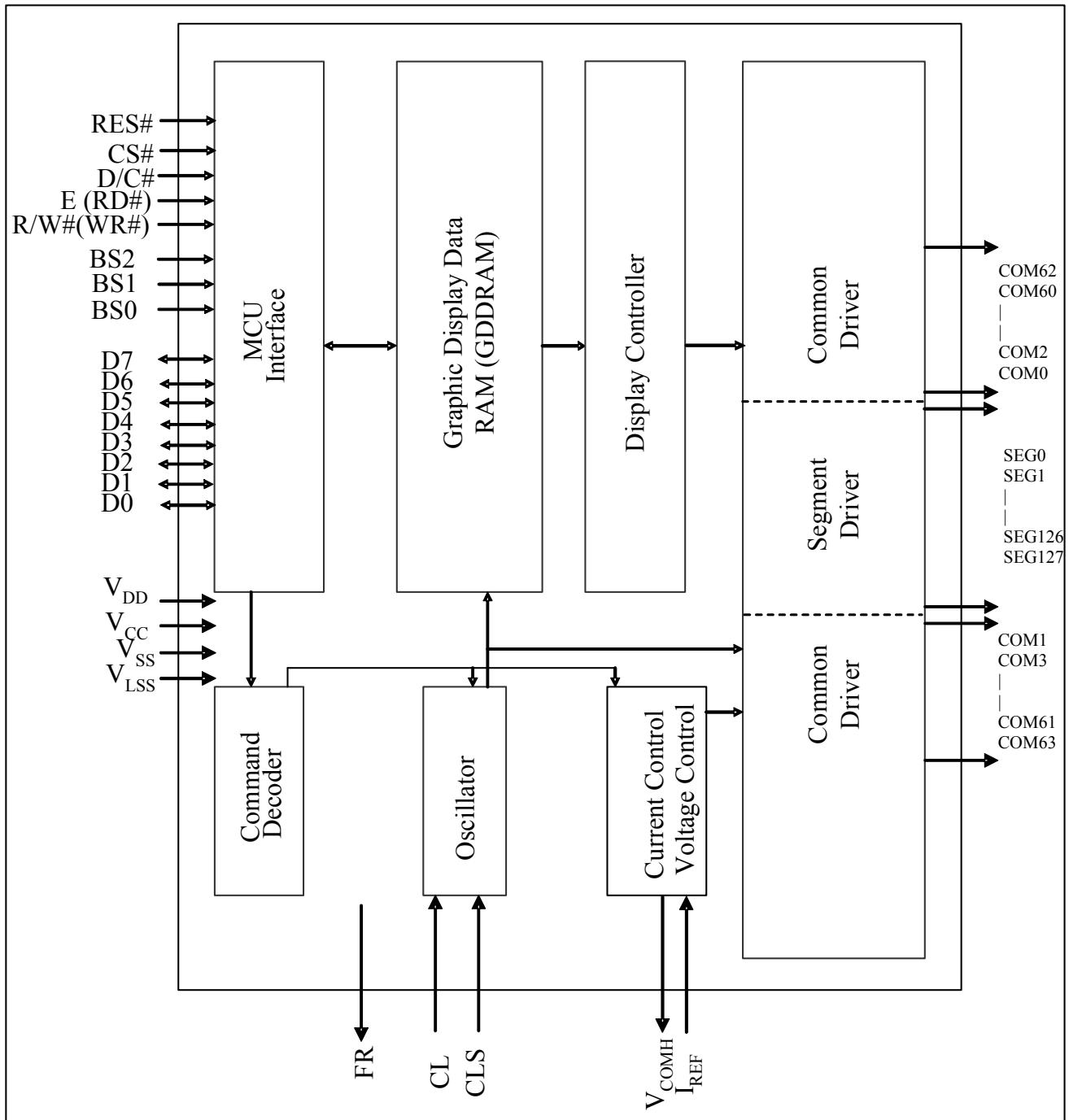
3 ORDERING INFORMATION

Table 3-1: Ordering Information

Ordering Part Number	SEG	COM	Package Form	Reference	Remark
SSD1306Z	128	64	COG	8	<ul style="list-style-type: none">◦ Min SEG pad pitch : 47um◦ Min COM pad pitch : 40um◦ Die thickness: 300 +/- 25um
SSD1306TR1	104	48	TAB	11, 56	<ul style="list-style-type: none">◦ 35mm film, 4 sprocket hole, Folding TAB◦ 8-bit 80 / 8-bit 68 / SPI / I²C interface◦ SEG, COM lead pitch 0.1mm x 0.997 =0.0997mm◦ Die thickness: 457 +/- 25um

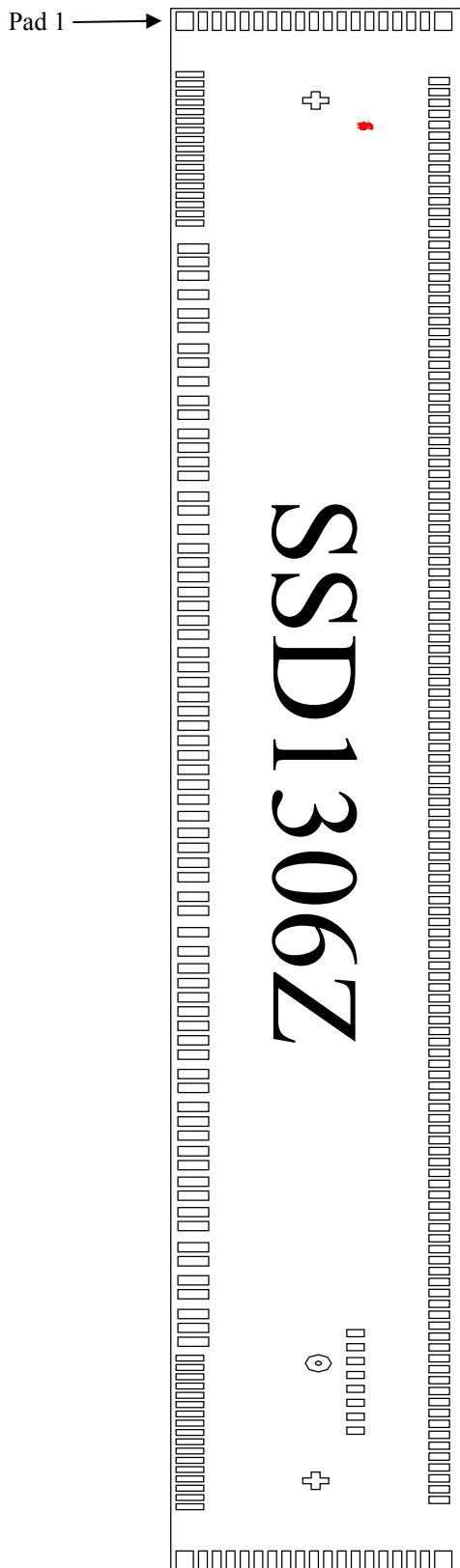
4 BLOCK DIAGRAM

Figure 4-1 SSD1306 Block Diagram



5 DIE PAD FLOOR PLAN

Figure 5-1 : SSD1306Z Die Drawing



Die size	6.76mm x 0.86mm
Die thickness	300 +/- 25um
Min I/O pad pitch	60um
Min SEG pad pitch	47um
Min COM pad pitch	40um
Bump height	Nominal 15um

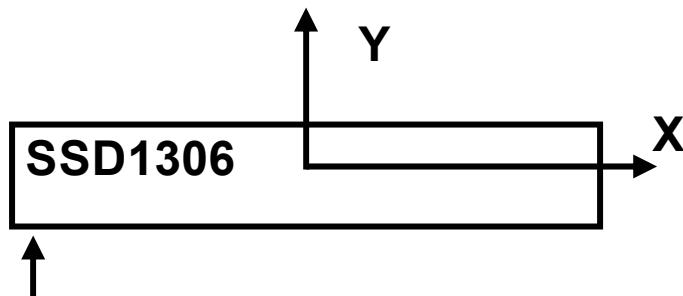
Bump size	
Pad 1, 106, 124, 256	80um x 50um
Pad 2-18, 89-105, 107-123, 257-273	25um x 80um
Pad 19-88	40um x 89um
Pad 125-255	31um x 59um
Pad 274-281 (TR pads)	30um x 50um

Alignment mark	Position	Size
+	(-2973, 0)	75um x 75um
+	(2973, 0)	75um x 75um
Circle	(2466.665, 7.575)	R37.5um, inner 18um
SSL Logo	(-2862.35, 144.82)	-

(For details dimension please see p.9)

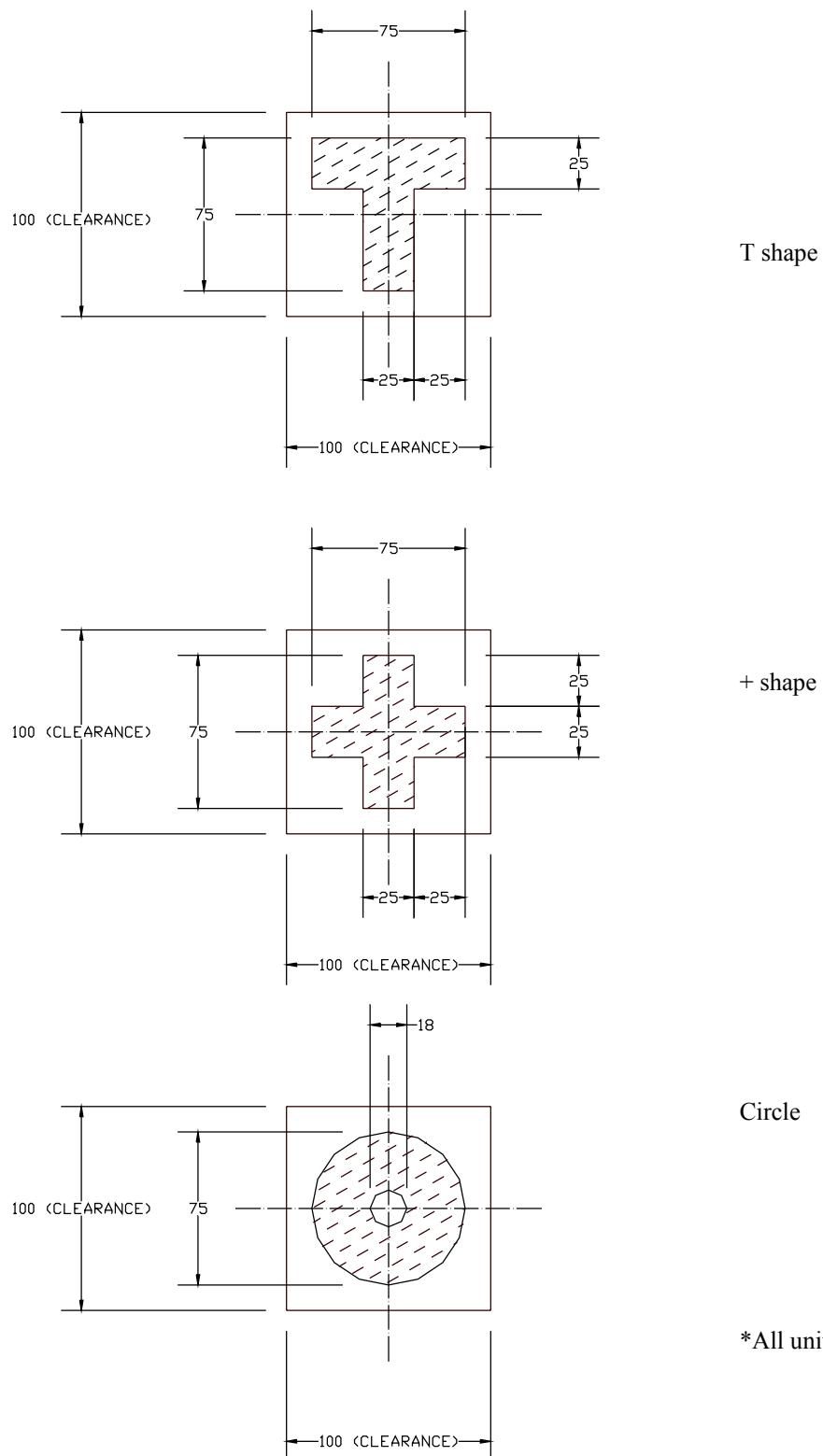
Note

- ⁽¹⁾ Diagram showing the Gold bumps face up.
- ⁽²⁾ Coordinates are referenced to center of the chip.
- ⁽³⁾ Coordinate units and size of all alignment marks are in um.
- ⁽⁴⁾ All alignment keys do not contain gold



Pad 1,2,3,...>281
Gold Bumps face up

Figure 5-2 : SSD1306Z alignment mark dimensions



*All units are in um

Table 5-1 : SSD1306Z Bump Die Pad Coordinates

Pad no.	Pad Name	X-pos	Y-pos
1	NC	-3315	-377.5
2	VSS	-3084.77	-362.5
3	COM49	-3044.77	-362.5
4	COM50	-3004.77	-362.5
5	COM51	-2964.77	-362.5
6	COM52	-2924.77	-362.5
7	COM53	-2884.77	-362.5
8	COM54	-2844.77	-362.5
9	COM55	-2804.77	-362.5
10	COM56	-2764.77	-362.5
11	COM57	-2724.77	-362.5
12	COM58	-2684.77	-362.5
13	COM59	-2644.77	-362.5
14	COM60	-2604.77	-362.5
15	COM61	-2564.77	-362.5
16	COM62	-2524.77	-362.5
17	COM63	-2484.77	-362.5
18	VCOMH	-2444.77	-362.5
19	NC	-2334.965	-352.83
20	C2P	-2278.265	-352.83
21	C2P	-2218.265	-352.83
22	C2N	-2136.715	-352.83
23	C2N	-2055.465	-352.83
24	C1P	-1995.465	-352.83
25	C1P	-1904.115	-352.83
26	CIN	-1844.115	-352.83
27	CIN	-1762.865	-352.83
28	VBAT	-1679.31	-352.83
29	VBAT	-1619.31	-352.83
30	VBREF	-1537.751	-352.83
31	BGGND	-1477.51	-352.83
32	VCC	-1416.01	-352.83
33	VCC	-1356.01	-352.83
34	VCOMH	-1266.955	-352.83
35	VCOMH	-1206.955	-352.83
36	VLSS	-1125.155	-352.83
37	VLSS	-1043.355	-352.83
38	VLSS	-983.355	-352.83
39	VSS	-920	-352.83
40	VSS	-856	-352.83
41	VSS	-796	-352.83
42	VDD	-732.645	-352.83
43	VDD	-672.645	-352.83
44	BS0	-595.655	-352.83
45	VSS	-531.955	-352.83
46	BS1	-467.655	-352.83
47	VDD	-403.155	-352.83
48	VDD	-342.555	-352.83
49	BS2	-279.705	-352.83
50	VSS	-215.705	-352.83
51	FR	-151.955	-352.83
52	CL	-89.815	-352.83
53	VSS	-25.665	-352.83
54	CS#	38.635	-352.83
55	RES#	109.835	-352.83
56	D/C#	182.425	-352.83
57	VSS	246.125	-352.83
58	R/W#	310.425	-352.83
59	E	373.125	-352.83
60	VDD	457.175	-352.83
61	VDD	517.175	-352.83
62	D0	609.275	-352.83
63	D1	692.475	-352.83
64	D2	765.675	-352.83
65	D3	828.875	-352.83
66	VSS	890.325	-352.83
67	D4	951.275	-352.83
68	D5	1013.315	-352.83
69	D6	1075.355	-352.83
70	D7	1137.395	-352.83
71	VSS	1220.735	-352.83
72	VSS	1280.735	-352.83
73	CLS	1362.585	-352.83
74	VDD	1425.285	-352.83
75	VDD	1485.885	-352.83
76	VDD	1553.185	-352.83
77	VDD	1613.185	-352.83
78	IREF	1684.585	-352.83
79	IREF	1744.585	-352.83
80	VCOMH	1815.585	-352.83

Pad no.	Pad Name	X-pos	Y-pos
81	VCOMH	1875.585	-352.83
82	VCC	1967.185	-352.83
83	VCC	2027.185	-352.83
84	VLSS	2109.185	-352.83
85	VLSS	2169.185	-352.83
86	VLSS	2254.185	-352.83
87	NC	2314.185	-352.83
88	NC	2374.185	-352.83
89	VSS	2444.77	-362.5
90	COM31	2484.77	-362.5
91	COM30	2524.77	-362.5
92	COM29	2564.77	-362.5
93	COM28	2604.77	-362.5
94	COM27	2644.77	-362.5
95	COM26	2684.77	-362.5
96	COM25	2724.77	-362.5
97	COM24	2764.77	-362.5
98	COM23	2804.77	-362.5
99	COM22	2844.77	-362.5
100	COM21	2884.77	-362.5
101	COM20	2924.77	-362.5
102	COM19	2964.77	-362.5
103	COM18	3004.77	-362.5
104	COM17	3044.77	-362.5
105	VSS	3084.77	-362.5
106	NC	3315	-377.5
107	COM16	3315	-325
108	COM15	3315	-285
109	COM14	3315	-245
110	COM13	3315	-205
111	COM12	3315	-165
112	COM11	3315	-125
113	COM10	3315	-85
114	COM9	3315	-45
115	COM8	3315	-5
116	COM7	3315	35
117	COM6	3315	75
118	COM5	3315	115
119	COM4	3315	155
120	COM3	3315	195
121	COM2	3315	235
122	COM1	3315	275
123	COM0	3315	315
124	NC	3315	367.5
125	NC	3055.5	356
126	SEQ0	3009.5	356
127	SEG1	2962.5	356
128	SEG2	2915.5	356
129	SEG3	2868.5	356
130	SEG4	2821.5	356
131	SEG5	2774.5	356
132	SEG6	2727.5	356
133	SEG7	2680.5	356
134	SEG8	2633.5	356
135	SEG9	2586.5	356
136	SEG10	2539.5	356
137	SEG11	2492.5	356
138	SEG12	2445.5	356
139	SEG13	2398.5	356
140	SEG14	2351.5	356
141	SEG15	2304.5	356
142	SEG16	2257.5	356
143	SEG17	2210.5	356
144	SEG18	2163.5	356
145	SEG19	2116.5	356
146	SEG20	2069.5	356
147	SEG21	2022.5	356
148	SEG22	1975.5	356
149	SEG23	1928.5	356
150	SEG24	1881.5	356
151	SEG25	1834.5	356
152	SFG26	1787.5	356
153	SEG27	1740.5	356
154	SEG28	1693.5	356
155	SEG29	1646.5	356
156	SEG30	1599.5	356
157	SEG31	1552.5	356
158	SEG32	1505.5	356
159	SEG33	1458.5	356
160	SEG34	1411.5	356

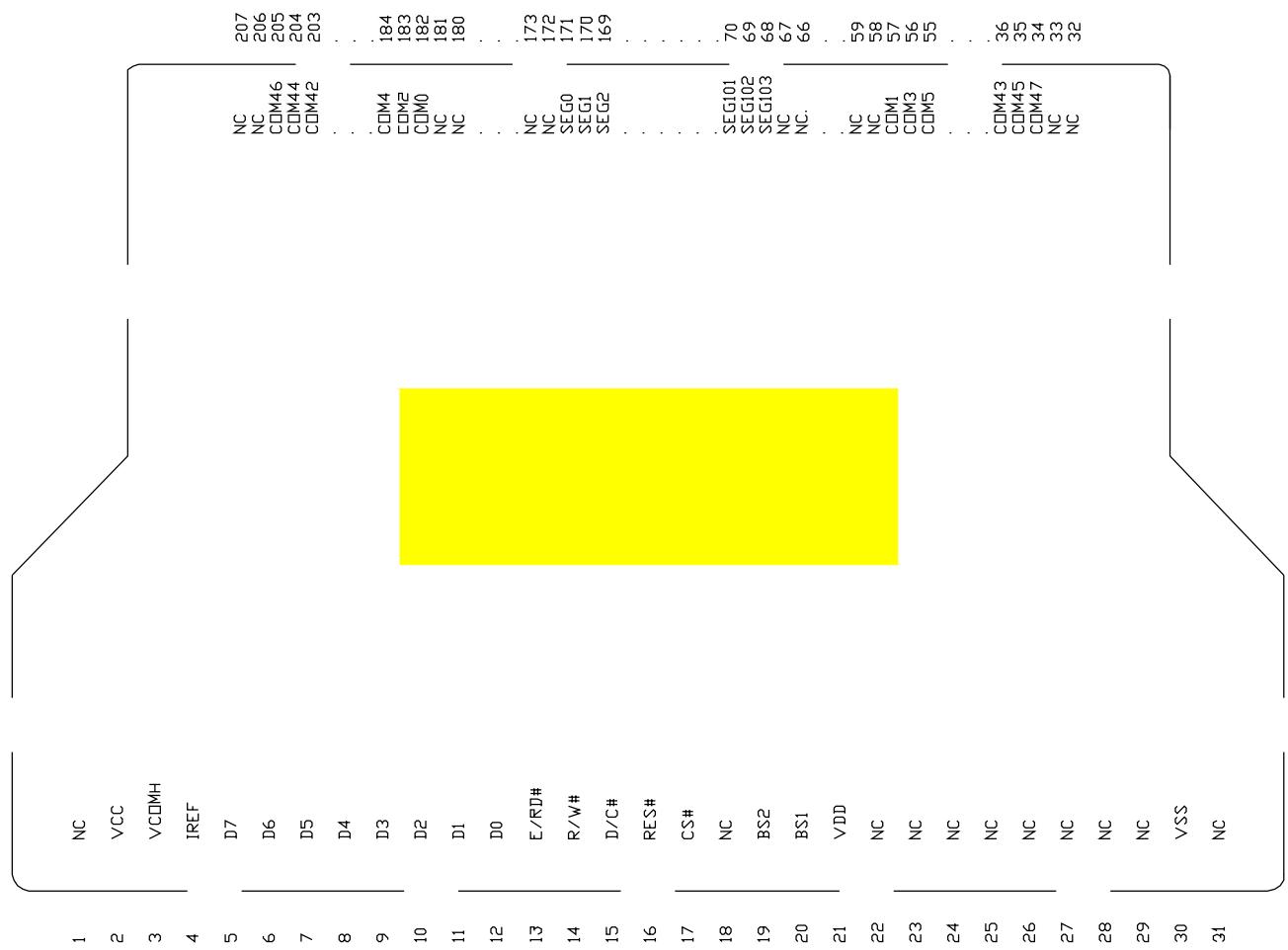
Pad no.	Pad Name	X-pos	Y-pos
161	SEG35	1364.5	356
162	SEG36	1317.5	356
163	SEG37	1270.5	356
164	SEG38	1223.5	356
165	SEG39	1176.5	356
166	SEG40	1129.5	356
167	SEG41	1082.5	356
168	SEG42	1035.5	356
169	SEG43	988.5	356
170	SEG44	941.5	356
171	SEG45	894.5	356
172	SEG46	847.5	356
173	SEG47	800.5	356
174	SEG48	753.5	356
175	SEG49	706.5	356
176	SEG50	659.5	356
177	SEG51	612.5	356
178	SEG52	565.5	356
179	SEG53	518.5	356
180	SEG54	471.5	356
181	SEG55	424.5	356
182	SEG56	377.5	356
183	SEG57	330.5	356
184	SEG58	283.5	356
185	SEG59	236.5	356
186	SEG60	189.5	356
187	SEG61	142.5	356
188	SEG62	95.5	356
189	SEG63	48.5	356
190	SEG64	1.5	356
191	SEG65	-45.5	356
192	SEG66	-92.5	356
193	SEG67	-139.5	356
194	SEG68	-186.5	356
195	SEG69	-233.5	356
196	SEG70	-280.5	356
197	SEG71	-327.5	356
198	SEG72	-374.5	356
199	SEG73	-421.5	356
200	SEG74	-468.5	356
201	SEG75	-515.5	356
202	SEG76	-562.5	356
203	SEG77	-609.5	356
204	SEG78	-656.5	356
205	SEG79	-703.5	356
206	SEG80	-750.5	356
207	SEG81	-797.5	356
208	SEG82	-844.5	356
209	SEG83	-891.5	356
210	NC	-940	356
211	SEG84	-988.5	356
212	SEG85	-1035.5	356
213	SEG86	-1082.5	356
214	SEG87	-1129.5	356
215	SEG88	-1176.5	356
216	SEG89	-1223.5	356
217	SEG90	-1270.5	356
218	SEG91	-1317.5	356
219	SEG92	-1364.5	356
220	SEG93	-1411.5	356
221	SEG94	-1458.5	356
222	SEG95	-1505.5	356
223	SEG96	-1552.5	356
224	SEG97	-1599.5	356
225	SEG98	-1646.5	356
226	SEG99	-1693.5	356
227	SEG100	-1740.5	356
228	SEG101	-1787.5	356
229	SEG102	-1834.5	356
230	SEG103	-1881.5	356
231	SEG104	-1928.5	356
232	SEG105	-1975.5	356
233	SEG106	-2022.5	356
234	SEG107	-2069.5	356
235	SEG108	-2116.5	356
236	SEG109	-2163.5	356
237	SEG110	-2210.5	356
238	SEG111	-2257.5	356
239	SEG112	-2304.5	356
240	SEG113	-2351.5	356

Pad no.	Pad Name	X-pos	Y-pos
241	SEG114	-2398.5	356
242	SEG115	-2445.5	356
243	SEG116	-2492.5	356
244	SEG117	-2539.5	356
245	SEG118	-2586.5	356
246	SEG119	-2633.5	356
247	SEG120	-2680.5	356
248	SEG121	-2727.5	356
249	SEG122	-2774.5	356
250	SEG123	-2821.5	356
251	SEG124	-2868.5	356
252	SEG125	-2915.5	356
253	SEG126	-2962.5	356
254	SEG127	-3009.5	3

6 PIN ARRANGEMENT

6.1 SSD1306TR1 pin assignment

Figure 6-1 : SSD1306TR1 Pin Assignment



Note:

⁽¹⁾ COM sequence (Split) is under command setting: DAh, 12h

Table 6-1 : SSD1306TR1 Pin Assignment Table

Pin no.	Pin Name	Pin no.	Pin Name	Pin no.	Pin Name
1	NC	81	SEG90	161	SEG10
2	VCC	82	SEG89	162	SEG9
3	VCOMH	83	SEG88	163	SEG8
4	IREF	84	SEG87	164	SEG7
5	D7	85	SEG86	165	SEG6
6	D6	86	SEG85	166	SEG5
7	D5	87	SEG84	167	SEG4
8	D4	88	SEG83	168	SEG3
9	D3	89	SEG82	169	SEG2
10	D2	90	SEG81	170	SEG1
11	D1	91	SEG80	171	SEG0
12	D0	92	SEG79	172	NC
13	E/RD#	93	SEG78	173	NC
14	R/W#	94	SEG77	174	NC
15	D/C#	95	SEG76	175	NC
16	RES#	96	SEG75	176	NC
17	CS#	97	SEG74	177	NC
18	NC	98	SEG73	178	NC
19	BS2	99	SEG72	179	NC
20	BS1	100	SEG71	180	NC
21	VDD	101	SEG70	181	NC
22	NC	102	SEG69	182	COM0
23	NC	103	SEG68	183	COM2
24	NC	104	SEG67	184	COM4
25	NC	105	SEG66	185	COM6
26	NC	106	SEG65	186	COM8
27	NC	107	SEG64	187	COM10
28	NC	108	SEG63	188	COM12
29	NC	109	SEG62	189	COM14
30	VSS	110	SEG61	190	COM16
31	NC	111	SEG60	191	COM18
32	NC	112	SEG59	192	COM20
33	NC	113	SEG58	193	COM22
34	COM47	114	SEG57	194	COM24
35	COM45	115	SEG56	195	COM26
36	COM43	116	SEG55	196	COM28
37	COM41	117	SEG54	197	COM30
38	COM39	118	SEG53	198	COM32
39	COM37	119	SEG52	199	COM34
40	COM35	120	SEG51	200	COM36
41	COM33	121	SEG50	201	COM38
42	COM31	122	SEG49	202	COM40
43	COM29	123	SEG48	203	COM42
44	COM27	124	SEG47	204	COM44
45	COM25	125	SEG46	205	COM46
46	COM23	126	SEG45	206	NC
47	COM21	127	SEG44	207	NC
48	COM19	128	SEG43		
49	COM17	129	SEG42		
50	COM15	130	SEG41		
51	COM13	131	SEG40		
52	COM11	132	SEG39		
53	COM9	133	SEG38		
54	COM7	134	SEG37		
55	COM5	135	SEG36		
56	COM3	136	SEG35		
57	COM1	137	SEG34		
58	NC	138	SEG33		
59	NC	139	SEG32		
60	NC	140	SEG31		
61	NC	141	SEG30		
62	NC	142	SEG29		
63	NC	143	SEG28		
64	NC	144	SEG27		
65	NC	145	SEG26		
66	NC	146	SEG25		
67	NC	147	SEG24		
68	SEG103	148	SEG23		
69	SEG102	149	SEG22		
70	SEG101	150	SEG21		
71	SEG100	151	SEG20		
72	SEG99	152	SEG19		
73	SEG98	153	SEG18		
74	SEG97	154	SEG17		
75	SEG96	155	SEG16		
76	SEG95	156	SEG15		
77	SEG94	157	SEG14		
78	SEG93	158	SEG13		
79	SEG92	159	SEG12		
80	SEG91	160	SEG11		

7 PIN DESCRIPTION

Key:

I = Input	NC = Not Connected
O = Output	Pull LOW= connect to Ground
I/O = Bi-directional (input/output)	Pull HIGH= connect to V _{DD}
P = Power pin	

Figure 7-1 Pin Description

Pin Name	Type	Description
V _{DD}	P	Power supply pin for core logic operation.
V _{CC}	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
V _{SS}	P	This is a ground pin.
V _{LSS}	P	This is an analog ground pin. It should be connected to V _{SS} externally.
V _{COMH}	O	The pin for COM signal deselected voltage level. A capacitor should be connected between this pin and V _{SS} .
V _{BAT}	P	Reserved pin. It should be connected to V _{DD} .
BGGND	P	Reserved pin. It should be connected to ground.
C1P/C1N C2P/C2N	I	Reserved pin. It should be kept NC.
V _{BREF}	P	Reserved pin. It should be kept NC.
BS[2:0]	I	MCU bus interface selection pins. Please refer to Table 7-1 for the details of setting.
I _{REF}	I	This is segment output current reference pin. A resistor should be connected between this pin and V _{SS} to maintain the I _{REF} current at 12.5 uA. Please refer to Figure 8-15 for the details of resistor value.
FR	O	This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used. Please refer to Section 8.4 for details usage.
CL	I	This is external clock input pin. When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and should be connected to V _{SS} . When internal clock is disabled (i.e. LOW in CLS pin), this pin is the external clock source input pin.
CLS	I	This is internal clock enable pin. When it is pulled HIGH (i.e. connect to V _{DD}), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.
RES#	I	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to V _{DD}) during normal operation.
CS#	I	This pin is the chip select input. (active LOW).

Pin Name	Type	Description
D/C#	I	<p>This is Data/Command control pin. When it is pulled HIGH (i.e. connect to V_{DD}), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register.</p> <p>In I²C mode, this pin acts as SA0 for slave address selection.</p> <p>When 3-wire serial interface is selected, this pin must be connected to V_{SS}.</p> <p>For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams: Figure 13-1 to Figure 13-5.</p>
E (RD#)	I	<p>When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to V_{DD}) and the chip is selected.</p> <p>When connecting to an 8080-series microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected.</p> <p>When serial or I²C interface is selected, this pin must be connected to V_{SS}.</p>
R/W#(WR#)	I	<p>This is read / write control input pin connecting to the MCU interface.</p> <p>When interfacing to a 6800-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH (i.e. connect to V_{DD}) and write mode when LOW.</p> <p>When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected.</p> <p>When serial or I²C interface is selected, this pin must be connected to V_{SS}.</p>
D[7:0]	IO	<p>These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus.</p> <p>When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC.</p> <p>When I²C mode is selected, D2, D1 should be tied together and serve as SDA_{out}, SDA_{in} in application and D0 is the serial clock input, SCL.</p>
TR0-TR6	-	Testing reserved pins. It should be kept NC.
SEG0 ~ SEG127	O	These pins provide Segment switch signals to OLED panel. These pins are V _{SS} state when display is OFF.
COM0 ~ COM63	O	These pins provide Common switch signals to OLED panel. They are in high impedance state when display is OFF.
NC	-	This is dummy pin. Do not group or short NC pins together.

Table 7-1 : MCU Bus Interface Pin Selection

SSD1306 Pin Name	I ² C Interface	6800-parallel interface (8 bit)	8080-parallel interface (8 bit)	4-wire Serial interface	3-wire Serial interface
BS0	0	0	0	0	1
BS1	1	0	1	0	0
BS2	0	1	1	0	0

Note

⁽¹⁾ 0 is connected to V_{SS}

⁽²⁾ 1 is connected to V_{DD}

8 FUNCTIONAL BLOCK DESCRIPTIONS

8.1 MCU Interface selection

SSD1306 MCU interface consist of 8 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 8-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 7-1 for BS[2:0] setting).

Table 8-1 : MCU interface assignment under different bus interface mode

Pin Name Bus Interface	Data/Command Interface								Control Signal				
	D7	D6	D5	D4	D3	D2	D1	D0	E	R/W#	CS#	D/C#	RES#
8-bit 8080	D[7:0]								RD#	WR#	CS#	D/C#	RES#
8-bit 6800	D[7:0]								E	R/W#	CS#	D/C#	RES#
3-wire SPI	Tie LOW			NC	SDIN	SCLK	Tie LOW		CS#	Tie LOW	RES#		
4-wire SPI	Tie LOW			NC	SDIN	SCLK	Tie LOW		CS#	D/C#	RES#		
I ² C	Tie LOW			SDA _{OUT}	SDA _{IN}	SCL	Tie LOW		SA0	RES#			

8.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.

The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

Table 8-2 : Control pins of 6800 interface

Function	E	R/W#	CS#	D/C#
Write command	↓	L	L	L
Read status	↓	H	L	L
Write data	↓	L	L	H
Read data	↓	H	L	H

Note

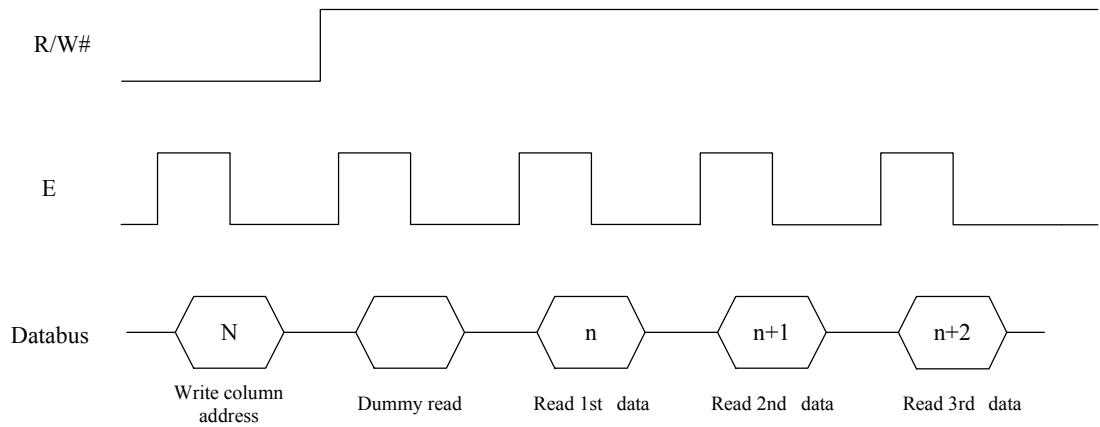
⁽¹⁾ ↓ stands for falling edge of signal

H stands for HIGH in signal

L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-1.

Figure 8-1 : Data read back procedure - insertion of dummy read



8.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write.
A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW.

A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 8-2 : Example of Write procedure in 8080 parallel interface mode

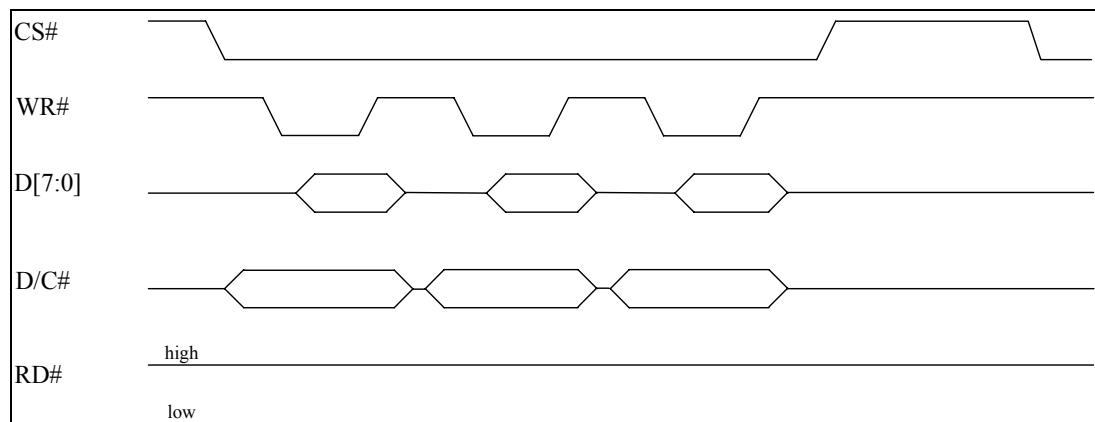


Figure 8-3 : Example of Read procedure in 8080 parallel interface mode

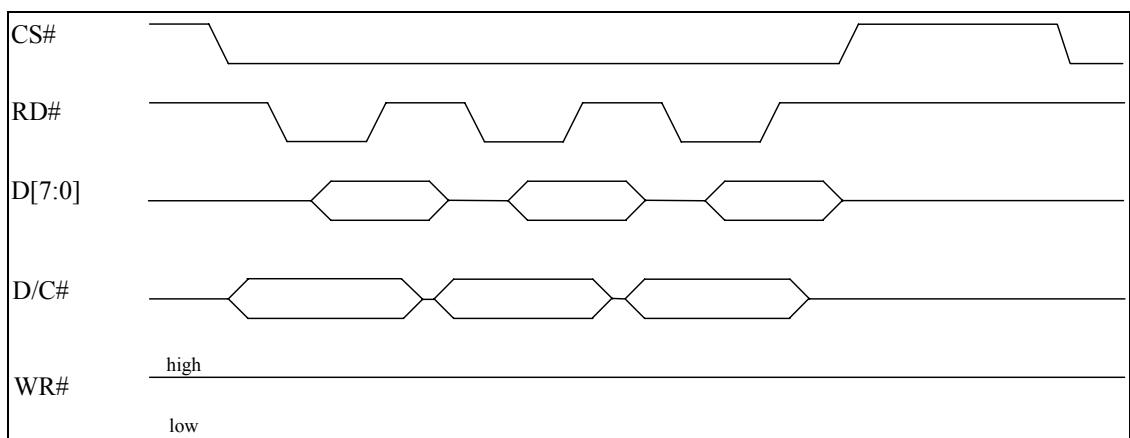


Table 8-3 : Control pins of 8080 interface

Function	RD#	WR#	CS#	D/C#
Write command	H	↑	L	L
Read status	↑	H	L	L
Write data	H	↑	L	H
Read data	↑	H	L	H

Note

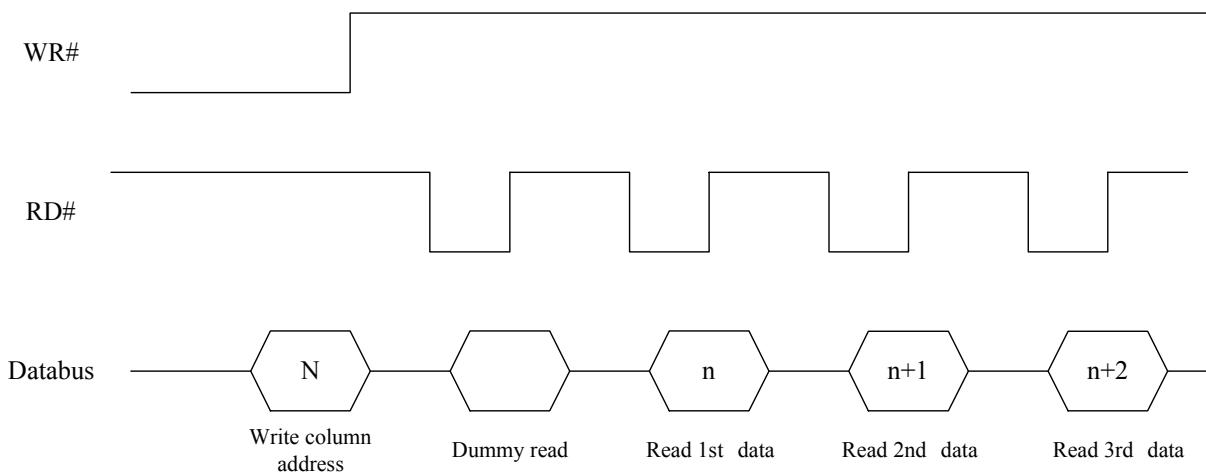
(¹) ↑ stands for rising edge of signal

(²) H stands for HIGH in signal

(³) L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-4.

Figure 8-4 : Display data read back procedure - insertion of dummy read



8.1.3 MCU Serial Interface (4-wire SPI)

The 4-wire serial interface consists of serial clock: SCLK, serial data: SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W# (WR#) can be connected to an external ground.

Table 8-4 : Control pins of 4-wire Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0
Write command	Tie LOW	Tie LOW	L	L	↑
Write data	Tie LOW	Tie LOW	L	H	↑

Note

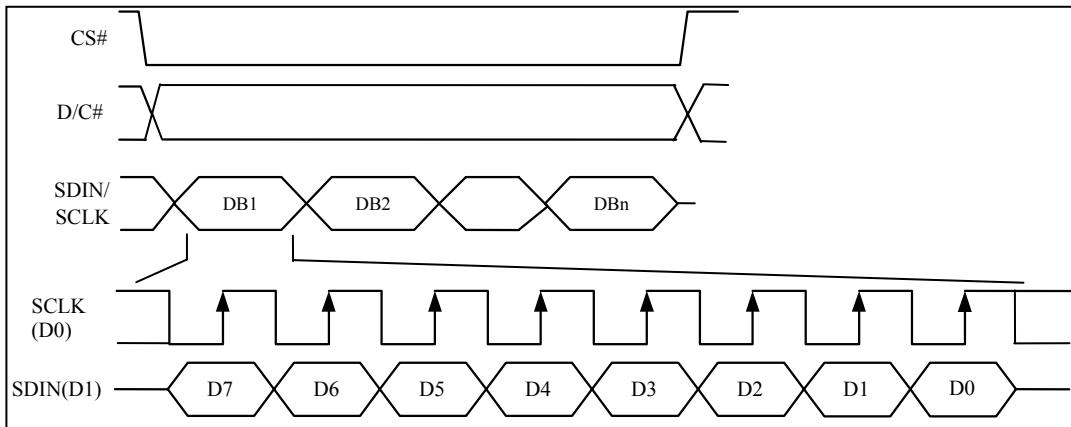
(¹) H stands for HIGH in signal

(²) L stands for LOW in signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock.

Under serial mode, only write operations are allowed.

Figure 8-5 : Write procedure in 4-wire Serial interface mode



8.1.4 MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#.

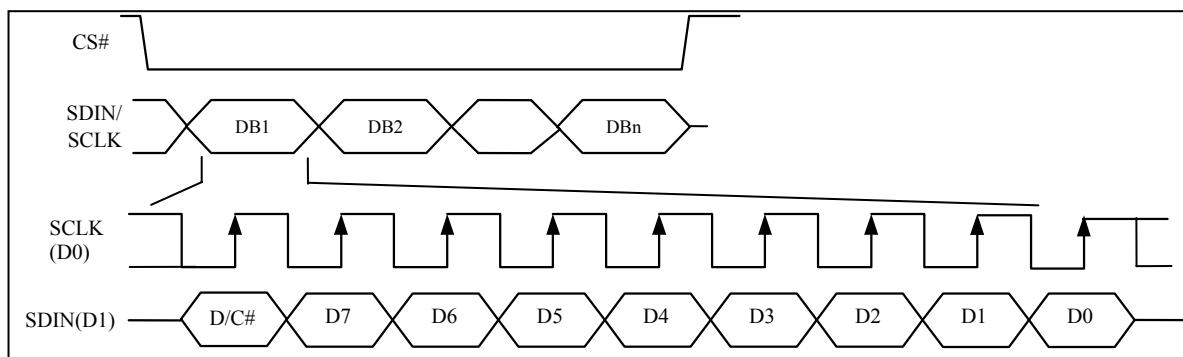
In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, R/W#(WR#), E and D/C# can be connected to an external ground.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0). Under serial mode, only write operations are allowed.

Table 8-5 : Control pins of 3-wire Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0	Note
Write command	Tie LOW	Tie LOW	L	Tie LOW	↑	(¹) L stands for LOW in signal
Write data	Tie LOW	Tie LOW	L	Tie LOW	↑	

Figure 8-6 : Write procedure in 3-wire Serial interface mode



8.1.5 MCU I²C Interface

The I²C communication interface consists of slave address bit SA0, I²C-bus data signal SDA (SDA_{OUT}/D₂ for output and SDA_{IN}/D₁ for input) and I²C-bus clock signal SCL (D₀). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)

SSD1306 has to recognize the slave address before transmitting or receiving any information by the I²C-bus. The device will respond to the slave address following by the slave address bit (“SA0” bit) and the read/write select bit (“R/W#” bit) with the following byte format,

b₇ b₆ b₅ b₄ b₃ b₂ b₁ b₀
0 1 1 1 1 0 SA0 R/W#

“SA0” bit provides an extension bit for the slave address. Either “0111100” or “0111101”, can be selected as the slave address of SSD1306. D/C# pin acts as SA0 for slave address selection.

“R/W#” bit is used to determine the operation mode of the I²C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

b) I²C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.

It should be noticed that the ITO track resistance and the pulled-up resistance at “SDA” pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in “SDA”.

“SDA_{IN}” and “SDA_{OUT}” are tied together and serve as SDA. The “SDA_{IN}” pin must be connected to act as SDA. The “SDA_{OUT}” pin may be disconnected. When “SDA_{OUT}” pin is disconnected, the acknowledgement signal will be ignored in the I²C-bus.

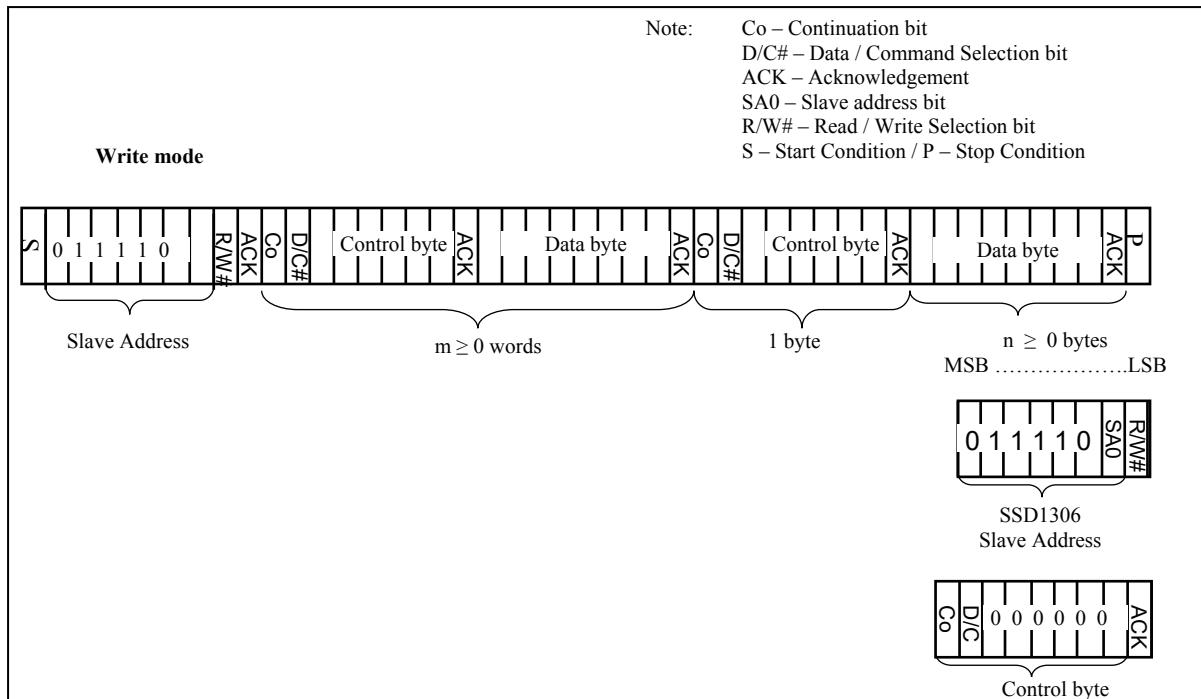
c) I²C-bus clock signal (SCL)

The transmission of information in the I²C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

8.1.5.1 I²C-bus Write data

The I²C-bus interface gives access to write data and command into the device. Please refer to Figure 8-7 for the write mode of I²C-bus in chronological order.

Figure 8-7 : I²C-bus data format



8.1.5.2 Write mode for I²C

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 8-8. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD1306, the slave address is either “b0111100” or “b0111101” by changing the SA0 to LOW or HIGH (D/C pin acts as SA0).
- 3) The write mode is established by setting the R/W# bit to logic “0”.
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 8-9 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six “0” ‘s.
 - a. If the Co bit is set as logic “0”, the transmission of the following information will contain data bytes only.
 - b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic “0”, it defines the following data byte as a command. If the D/C# bit is set to logic “1”, it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 6) Acknowledge bit will be generated after receiving each control byte or data byte.
- 7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 8-8. The stop condition is established by pulling the “SDA in” from LOW to HIGH while the “SCL” stays HIGH.